DNS glue coating and developing machine SK-W80A-BVP

Technical Specification

1. Equipment configuration: 8 inches

Serial number	name	amount)
1	ID: Open cassette unit	4
2	TR: Transport Robot Wafer Transfer Arm	2
3	SD: Develop unit	2
4	SC: Coat unit	3
5	AH: HMDS Tackifier Unit	1
6	CP: Cool Plate	5
7	HP: Hot Plate (Hot Plate Oven Unit)	8

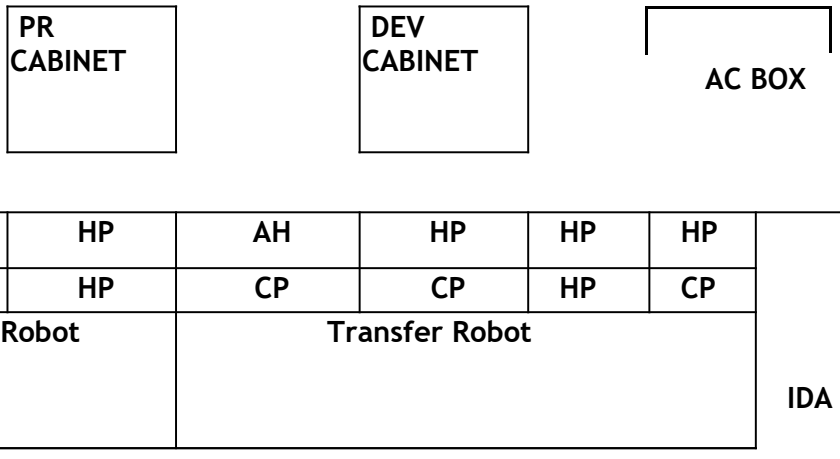
2. Equipment performance indicators:

Serial number	project	describe
1	Open cassette unit	Can hold 4 Casstes; can automatically detect the wafer storage position The way to put in and out the flower basket and the order of taking out the flowers can be set
2	TR: Wafer Transfer Arm	IDA robot wait to SD/SC/CP/HP/RO functional unit transmission
3	SD: Development chamber	Wafer fixing method: vacuum adsorption. Development spray, pure water, back flushing
4	SC: Glue chamber	Vacuum adsorption, 3 glue pumps, 2-way glue, EBR, back cleaning
5	Liquid supply system	1 set of automatic liquid supply;
6	Main control unit	1. 6 IDA, TR, SPIN, hot and cold plate unit control boards.2. SPIN servo controller 5 sets 3. TR robot drive box 2 sets 4. 1 main control computer, 1 human-machine interface screen
7	Equipment process menu	Can edit and store 99 process menus (programs 1-99)
8	Computer host	NEC 9821A Industrial Computer
9	Spin Motor	Japan Yaskawa Association circulation servo motor: (0～8000)rpm adjustable Accuracy: 0-2000rpm, error: 0.05%; 2000-5000rpm, error: 0.02%
10	data monitoring	Rinse 1 Nozzle, Rinse 2 Nozzle, Real-time flow monitoring/SPIN single Yuan

11	Wafer recycling system	1. After power off and restart, it can automatically detect whether there is silicon wafer and automatically put the silicon wafer Recycled into Cassette No. 1.
12	Robot position correction	The up and down, front and back, and rotation positions of the robot can be set and recorded through data. Memory. Accuracy: 0.1mm.
13	HP Hot Plate Oven	23-250 degrees; accuracy ±0.5 degrees, process time adjustable, temperature compensated
14	CP Cold Plate Unit	23±0.5 degrees, process time adjustable, temperature compensated

3. Equipment power conditions:

Device Name	project	describe
Glue coating and developing machine SK-W80A-BVP	Power Requirements	1Φ100VAC, 5KW/14.5A; 1Φ 200VAC, 2.4KW/3A 60HZ
	Environmental requirements	Temperature: 23±5℃, humidity: [illegible] 65%
	CDA Requirements	0.4-0.7mpa, 3m³/h
	Vacuum requirements	≥ 45 mmHg
	N2 Requirements	≥0.7mpa, 2m³/h high purity
	Heat exhaust	200m³/h
	Pure water requirements	≥0.2Mpa, 3m³/h



DEV	**DEV**	**Coat**	**Coat**	**Coat**		
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